

# MA72

## Silicon epitaxial planer type

For band switching

### ■ Features

- Low forward dynamic resistance  $r_f$
- Less voltage dependence of diode capacity  $C_D$
- Mini package, enabling down-sizing of the equipment and automatic insertion through taping

### ■ Absolute Maximum Ratings (Ta= 25°C)

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	$V_R$	35	V
Forward current (DC)	$I_F$	100	mA
Operating ambient temperature	$T_{opr}^*$	- 25 to + 85	°C
Storage temperature	$T_{stg}$	- 55 to +150	°C

\* Maximum ambient temperature during operation

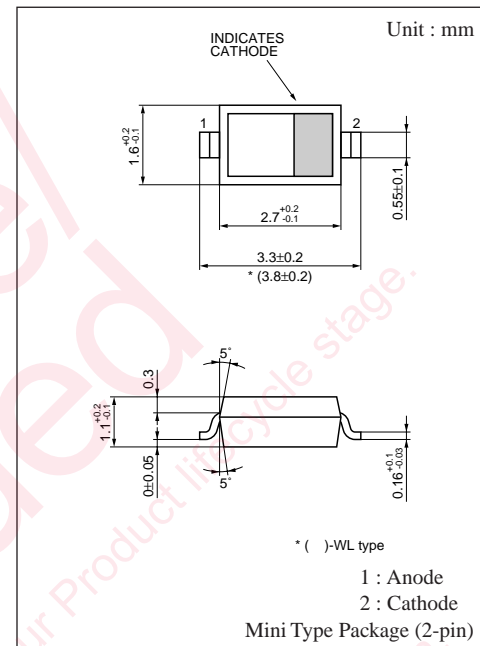
### ■ Electrical Characteristics (Ta= 25°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	$I_R$	$V_R= 33V$		0.01	100	nA
Forward voltage (DC)	$V_F$	$I_F=100mA$		0.88	1	V
Diode capacitance	$C_D$	$V_R= 6V, f=1MHz$		1.3	2	pF
Forward dynamic resistance	$r_f^*$	$I_F= 2mA, f=100MHz$		0.78	1.15	$\Omega$

Note 1 : Rated input/output frequency : 100MHz

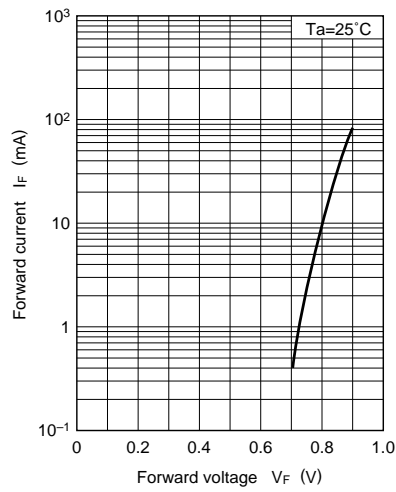
2 : \*  $r_f$  measurement device : YHP MODEL 4191A RF IMPEDANCE ANALYZER

### ■ Marking

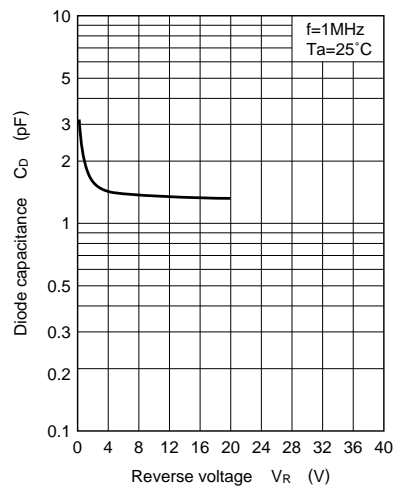


Marking Symbol : 4A

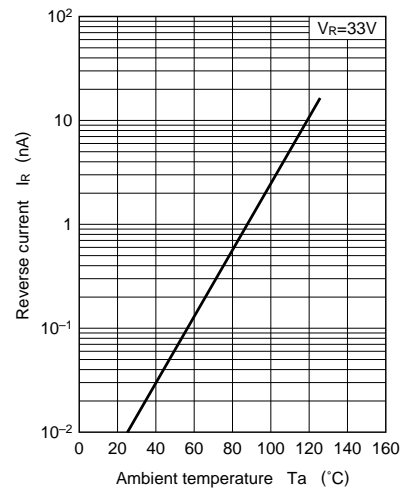
$I_F - V_F$



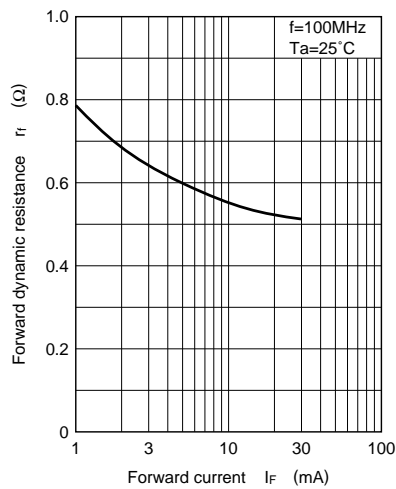
$C_D - V_R$



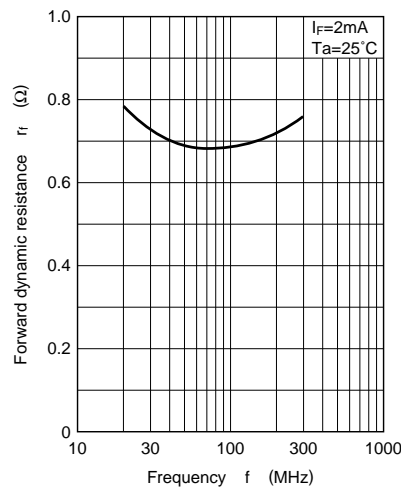
$I_R - T_a$



$r_f - I_F$



$r_f - f$



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